

HLT3500 Thermal Conductive Gel

BENEFITS AND FEATURES

- Low contact resistance
- Easy to dispense and rework
- High compressibility for low stress applications
- Long-term reliability
- Less oil separation
- No pump out and cracking

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Memory & power modules

OVERVIEW

Honeywell HLT3500 is two-part, dispensable thermally conductive gel, which offer long-term reliability and superior softness. The enhanced bonding force between the polymer base and the filler largely improves the thermally conductive gel oil separation issue in storage. Prior to curing, the material maintains good thixotropic characteristics and low viscosity to be easily dispensed. The product can be cured in short time after two-component mixing at room temperature. The high compressibility minimizes thermal resistance at interfaces, while maintaining excellent performance during reliability testing.

STORAGE & USE

- Shelf life 6 months at 0-35°C,
≤65%RH

Property	HLT3500	Test Method
Color	Part A: White Part B: Blue	Visual
Mix Ratio	1:1	by Volume
Thermal Conductivity (W/m-K)	3.5	ASTM D5470
Thermal Impedance (°C-in ² /W) (1mm@10psi, Typical Value)	0.50	ASTM D5470
Viscosity (Pa·s@25°C)	200~400	ASTM D2196 Brookfield Viscometer, #7 spindle@10rpm
Density(g/cm ³)	3.1	ASTM D792
Hardness (Shore00)	50	ASTM D2240
Minimum BLT (µm)	100	HON Internal
Working Time@25°C (h)	2.0	HON Internal
Curing Time	@25°C (h)	18.0
	@120°C (h)	0.5
Dielectric Strength (KV/mm)	10	ASTM D149
Volume Resistivity (ohm-cm)	1.0×10 ¹³	ASTM D257
Flammability Rating	V-0(Equivalent)	UL 94
Operating Temperature (°C)	-40~150	HON Internal

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

USA: 1-509-252-2102

China: 400-840-2233

Germany: 49-5137-999-9199

Japan: 81-3-6730-7092

Korea: 82-2-3483-5076

Singapore: 65-6580-3593

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